



GUH Circuit Industry (PG) Sdn Bhd

SINGLE SIDED CAPABILITIES

Capabilities (能力)	MP Capabilities (量产能力)	Sample Capabilities (样品能力)
Layer Count (最大层数)	1 Layer	1 Layer
PCB Thickness (板厚范围)	0.8mm ~ 1.6mm	0.8mm ~ 1.6mm
Minimum Mechanical Drill Size (最小钻径)	0.20mm	0.15mm
Hole Diameter Tolerance (孔径公差)	NPTH $\pm 50\mu\text{m}$	NPTH $\pm 50\mu\text{m}$
Drill Hole Accuracy (孔位精度)	$\pm 50\mu\text{m}$	$\pm 50\mu\text{m}$
Copper Thickness (铜厚范围)	1oz , 2oz	1oz , 2oz
Minimum Line Width / Spacing (最小线宽/线距)	180 μm / 180 μm	180 μm / 180 μm
Solder Mask Registration (阻焊对位精度)	$\pm 125\mu\text{m}$	$\pm 125\mu\text{m}$
Minimum Solder Bridge (最小阻焊桥)	> 0.40 mm	> 0.40 mm
Punching Tolerance (Punch 成型尺寸公差)	$\pm 200\mu\text{m}$	$\pm 200\mu\text{m}$
CNC Tolerance (CNC 成型尺寸公差)	$\pm 100\mu\text{m}$	$\pm 100\mu\text{m}$
CNC Process (成型加工) • Hole to Edge (孔到板边) • Edge to Edge (边到板边) • Circuit to Edge (线路到板边)	$\geq 1.20 \text{ mm}$ $\geq 1.00 \text{ mm}$ $\geq 0.15 \text{ mm}$	$\geq 1.20 \text{ mm}$ $\geq 1.00 \text{ mm}$ $\geq 0.15 \text{ mm}$
Production Panel (最大生产板尺寸)	510mm X 610mm	510mm X 610mm
Surface Finishing (表面处理)	Flux, OSP, ENIG	Flux, OSP, ENIG
Special Capability (特殊工艺)	Carbon, Peelable Mask	Carbon, Peelable Mask

~ The above production capabilities serve as a general guideline and is subject to change ~